



PCBA Manufacturing Capability

Item	Capability
Components	Passive Down to 0201 size BGA and VFBGA Leadless Chip Carriers/CSP Double-sided SMT Assembly Fine Pitch to 0.8mils BGA Repair and Reball Part Removal and Replacement
Quantity	Prototype & Low Volume PCB Assembly, from 1 Board to 250, or up to 1000 and customized
Type of Assembly	SMT, Thru-hole
Solder Type	Water Soluble Solder Paste, Leaded and Lead-Free
Bare Board Size	Smallest: 0.25*0.25 inches Largest: 20*20 inches
File Formate	Gerber files, Pick-N-Place file, Bill of Materials
Types of Service	Turn-key,partial turn-key or consignment
Component packaging	Cut Tape,Tube,Reels,Loose Parts
Turn Time	Same day service to 15 days service
Testing	Flying Probe Test, X-ray Inspection AOI Test
PCB assembly process	Drilling----Exposure-----Plating-----Etaching & Stripping---Punching-- ---Electrical Testing-----SMT-----Wave Soldering-----Assembling--- ICT-----Function Testing-----Temperature & Humidity Testing
Advantages	<p>----Professional Surface-mounting and Through-hole soldering technology;</p> <p>----Various sizes like 1206,0805,0603 components SMT technology;</p> <p>----ICT(In Circuit Test),FCT(Functional Circuit Test);</p> <p>----PCB Assembly With UL,CE,FCC,Rohs Approval;</p> <p>----Nitrogen gas reflow soldering technology for SMT;</p> <p>----High Standard SMT&Solder Assembly Line;</p> <p>----High density interconnected board placement technology capacity.</p>